



SOT1069-2

HWSO8: plastic thermal enhanced very very thin small outline package, no leads; 8 terminals;

10 June 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | D (double) |
| Package type descriptive code | HWSO8 |
| Package type industry code | HWSO8 |
| Package style descriptive code | HWSO8 (thermal enhanced very very thin small outline; no leads) |
| Package body material type | P (plastic) |
| IEC package outline code | - - - |
| JEDEC package outline code | MO-229 |
| JEITA package outline code | - - - |
| Mounting method type | S (surface mount) |
| Issue date | 25-5-2009 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D | package length | 1.9 | - | 2 | 2.1 | mm |
| E | package width | 2.9 | - | 3 | 3.1 | mm |
| A | seated height | 0.7 | - | 0.75 | 0.8 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 8 | - | |

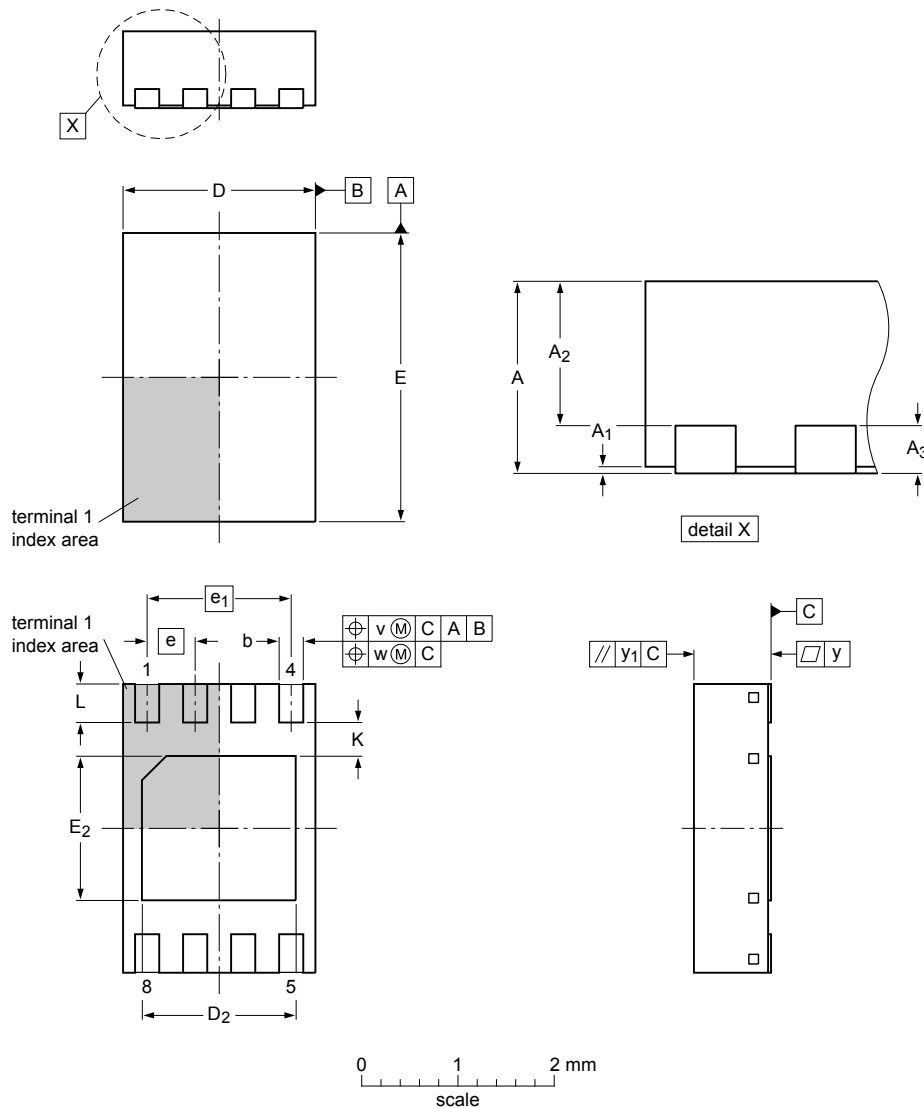


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2. Package outline

HWSO8: plastic thermal enhanced very very thin small outline package; no leads; 8 terminals; body 2 x 3 x 0.75 mm

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Dimensions

| Unit | A ⁽¹⁾ | A ₁ | A ₂ | A ₃ | b | D ⁽¹⁾ | D ₂ | E ⁽¹⁾ | E ₂ | e | e ₁ | K | L | v | w | y | y ₁ |
|------|------------------|----------------|----------------|----------------|------|------------------|----------------|------------------|----------------|-----|----------------|------|------|-----|------|------|----------------|
| max | 0.80 | 0.05 | 0.65 | | 0.30 | 2.1 | 1.6 | 3.1 | 1.6 | | | 0.40 | 0.45 | | | | |
| nom | 0.75 | 0.02 | 0.55 | 0.2 | 0.25 | 2.0 | 1.5 | 3.0 | 1.5 | 0.5 | 1.5 | 0.35 | 0.40 | 0.1 | 0.05 | 0.05 | 0.05 |
| min | 0.70 | 0.00 | 0.45 | | 0.18 | 1.9 | 1.4 | 2.9 | 1.4 | | | 0.30 | 0.35 | | | | |

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1069-2_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|--------|-------|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT1069-2 | --- | MO-229 | --- | | -09-11-18- 12-04-18 |

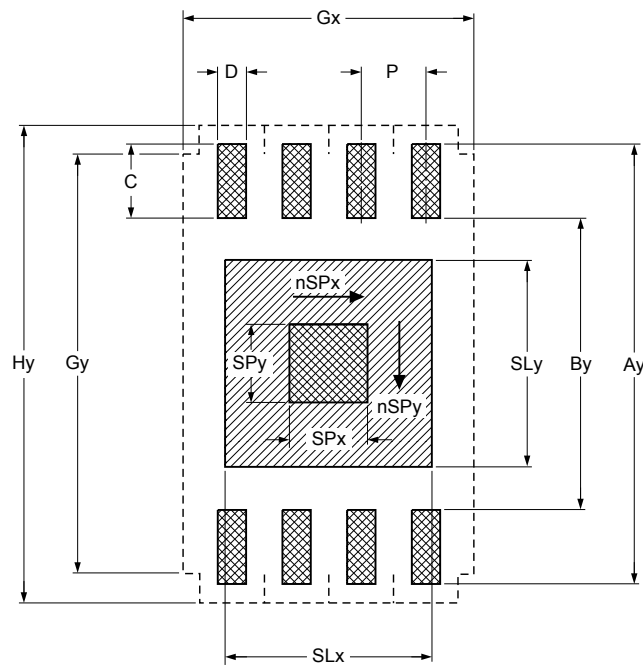
Fig. 1. Package outline HWSO8 (SOT1069-2)

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3. Soldering

Footprint information for reflow soldering of HWSO8 package

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- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area

DIMENSIONS in mm

| P | Ay | By | C | D | SLx | SLy | SPx | SPy | Gx | Gy | Hy | nSPx | nSPy |
|------------|----------------------|-----|-------|------|-----|-----|-----|-----|------|------|-----|--------------|------|
| 0.5 | 3.45 | 2.2 | 0.625 | 0.25 | 1.6 | 1.6 | 0.6 | 0.6 | 2.25 | 3.25 | 3.7 | 1 | 1 |
| Issue date | 12-02-09 12-02-22 | | | | | | | | | | | sot1069-2_fr | |

Fig. 2. Reflow soldering footprint for HWSO8 (SOT1069-2)

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4. Legal information

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